

## **PRODUCT/PROCESS CHANGE NOTICE (PCN)**

PCN #: Product Affected Date Effective: Contact: Title: Phone #:	IDT74SSTU3		MEANS OF D Product Ma Back Mark Date Code Other Attachment::	:
Fax #:	(408)-492-8362		Samples:	Available upon request.
E-mail:	bimla.paul@idt.com		Sumpress	
DESCRIPTION AND PURPOSE OF CHANGE:   Die Technology   Wafer Fabrication Process Maximum frequency is improved from 270 MHz to 340 MHz. This is a data sheet   Assembly Process change only. There is no change in die technology, process or design.   Equipment IDTCSPU877, IDTCSPU877A   Testing IDT74SSTU32864, IDT74SSTU32864A   Manufacturing Site IDT74SSTU32864C, IDT74SSTU32864D   Data Sheet Other				
<b>RELIABILITY/QUALIFICATION SUMMARY:</b> There is no change in quality and reliability of the affected parts.				
CUSTOMER ACKNOWLEDGMENT OF RECEIPT: IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable. IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.				
Customer:			Approva	l for shipments prior to effective date.
Name/Date:		E-1	Mail Address:	
Title:		Ph	one#/Fax#:	
CUSTOMER COMMENTS:				
IDT ACKNOWLEDGMENT OF RECEIPT:				
RECD. BY:			DATE:	